

**ISP1105/1106** 

Advanced USB transceivers Rev. 10 — 28 September 2009

Product data sheet

#### **General description** 1.

The ISP1105/1106 range of Universal Serial Bus (USB) transceivers are compliant with the Universal Serial Bus Specification Rev. 2.0. They can transmit and receive serial data at both full-speed (12 Mbit/s) and low-speed (1.5 Mbit/s) data rates. The ISP1105/1106 range can be used as a USB device transceiver or a USB host transceiver.

They allow USB Application Specific ICs (ASICs) and Programmable Logic Devices (PLDs) with power supply voltages from 1.65 V to 3.6 V to interface with the physical layer of the Universal Serial Bus. They have an integrated 5 V-to-3.3 V voltage regulator for direct powering via the USB supply V<sub>BUS</sub>.

ISP1105 allows single-ended and differential input modes selectable by a MODE input and it is available in HVQFN16 and HBCC16 packages. ISP1106 allows only differential input mode and is available in both TSSOP16 and HBCC16 packages.

The ISP1105/1106 are ideal for portable electronics devices such as mobile phones, digital still cameras, Personal Digital Assistants (PDA) and Information Appliances (IA).

#### 2. **Features**

- Complies with Universal Serial Bus Specification Rev. 2.0
- Can transmit and receive serial data at both full-speed (12 Mbit/s) and low-speed (1.5 Mbit/s) data rates
- Integrated bypassable 5 V-to-3.3 V voltage regulator for powering via USB V<sub>BUS</sub>
- V<sub>BUS</sub> disconnection indication through VP and VM
- Used as a USB device transceiver or a USB host transceiver
- Stable RCV output during SE0 condition
- Two single-ended receivers with hysteresis
- Low-power operation
- Supports an I/O voltage range from 1.65 V to 3.6 V
- ±12 kV ESD protection at the D+, D-, V<sub>CC(5.0)</sub> and GND pins
- Full industrial operating temperature range from -40 °C to +85 °C
- Available in small HBCC16, HVQFN16 (only ISP1105) and TSSOP16 (only ISP1106) packages

The ISP1105 HBCC16 and HVQFN16 are lead-free and halogen-free. The ISP1106 HBCC16 is lead-free.





## 3. Applications

- Portable electronic devices, such as:
  - Mobile phone
  - Digital still camera
  - Personal Digital Assistant (PDA)
  - Information Appliance (IA).

### 4. Ordering information

#### Table 1.Ordering information

Commercial product code	Package description	Packing	Minimum sellable quantity
ISP1105BSTM	HVQFN16; 16 terminals; body $3 \times 3 \times 0.85$ mm	13 inch tape and reel non-dry pack	6000 pieces
ISP1105WTS	HBCC16; 16 terminals; body $3 \times 3 \times 0.65$ mm	7 inch tape and reel non-dry pack	1400 pieces
ISP1105WTM	HBCC16; 16 terminals; body $3 \times 3 \times 0.65$ mm	13 inch tape and reel non-dry pack	6000 pieces
ISP1106WTS	HBCC16; 16 terminals; body $3 \times 3 \times 0.65$ mm	7 inch tape and reel non-dry pack	1400 pieces
ISP1106DHTM	TSSOP16; 16 leads; body width 4.4 mm	13 inch tape and reel non-dry pack	2500 pieces

### 4.1 Ordering options

Table 2.	Selection guide	
Product	Package	Description
ISP1105	HVQFN16 and HBCC16	supports both single-ended and differential input modes; see <u>Table 5</u> and <u>Table 6</u> .
ISP1106	TSSOP16 and HBCC16	supports only the differential input mode; see <u>Table 6</u> .



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### 5. Block diagram





### 6. Pinning information

#### 6.1 Pinning







### 6.2 Pin description

Symbol <sup>[1]</sup>	Pin				Туре	Description
-	ISP110	5	ISP110	6	-	
	BSTM		DHTM	WTS	_	
OE	1	1	3	1	I	output enable input (CMOS level with respect to $V_{CC(I/O)}$ , active LOW) enables the transceiver to transmit data on the USB bus input pad; push pull; CMOS
RCV	2	2	4	2	0	differential data receiver output (CMOS level with respect to $V_{CC(I/O)}$ ): driven LOW when input SUSPND is HIGH; the output state of RCV is preserved and stable during an SE0 condition
		_		_	~	output pad; push pull; 4 mA output drive; CMOS
VP	3	3	5	3	0	single-ended D+ receiver output (CMOS level with respect to $V_{CC(I/O)}$ ) for external detection of single-ended zero (SE0), error conditions, speed of connected device; driven HIGH when no supply voltage is connected to $V_{CC(5.0)}$ and $V_{reg(3.3)}$
					_	output pad; push pull; 4 mA output drive; CMOS
VM	4	4	6	4	0	single-ended D– receiver output (CMOS level with respect to V <sub>CC(I/O)</sub> ) for external detection of single-ended zero (SE0), error conditions, speed of connected device; driven HIGH when no supply voltage is connected to V <sub>CC(5.0)</sub> and V <sub>reg(3.3)</sub>
						output pad; push pull; 4 mA output drive; CMOS
SUSPND	5	5	7	5	I	suspend input (CMOS level with respect to $V_{CC(I/O)}$ ); a HIGH level enables low-power state while the USB bus is inactive and drives output RCV to a LOW level
						input pad; push pull; CMOS
MODE	6	6	-	-	I	mode input (CMOS level with respect to $V_{CC(I/O)}$ ); a HIGH level enables the differential input mode (VPO, VMO) whereas a LOW level enables a single-ended input mode (VO, FSE0); see <u>Table 5</u> and <u>Table 6</u>
						input pad; push pull; CMOS
GND	die pad	die pad	8	6	-	ground supply <sup>[2]</sup>
V <sub>CC(I/O)</sub>	7	7	9	7	-	supply voltage for digital I/O pins (1.65 V to 3.6 V). When V <sub>CC(I/O)</sub> is not connected, the (D+, D–) pins are in three-state; this supply pin is totally independent of V <sub>CC(5.0)</sub> and V <sub>reg(3.3)</sub> and must never exceed the V <sub>reg(3.3)</sub> voltage
SPEED	8	8	10	8	I	speed selection input (CMOS level with respect to $V_{CC(I/O)}$ ); adjusts the slew rate of differential data outputs D+ and D– according to the transmission speed
						LOW — low-speed (1.5 Mbit/s)
						HIGH — full-speed (12 Mbit/s)
						input pad; push pull; CMOS
D-	9	9	11	9	AI/O	negative USB data bus connection (analog, differential); for low-spee mode connect to pin $V_{pu(3.3)}$ via a 1.5 $k\Omega$ resistor
D+	10	10	12	10	AI/O	positive USB data bus connection (analog, differential); for full-speed mode connect to pin $V_{pu(3.3)}$ via a 1.5 k $\Omega$ resistor



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Symbol <sup>[1]</sup>	Pin	Pin			Туре	Description	
	ISP110	5	ISP110	6			
	BSTM	WTS, WTM	DHTM	WTS			
VPO/VO	11	11	-	-	I	driver data input (CMOS level with respect to $V_{CC(I/O)}$ , Schmitt trigger)	
VPO	-	-	13	11		see Table 5 and Table 6	
VO	-	-	-	-		input pad; push pull; CMOS	
VMO/FSE0	12	12	-	-	I	driver data input (CMOS level with respect to $V_{CC(I/O)}$ , Schmitt trigger)	
VMO	-	-	14	12		see <u>Table 5</u> and <u>Table 6</u>	
FSE0	-	-	-	-		input pad; push pull; CMOS	
V <sub>reg(3.3)</sub>	13	13	15	13	-	internal regulator option: regulated supply voltage output (3.0 V to 3.6 V) during 5 V operation; a decoupling capacitor of at leas 0.1 $\mu$ F is required	
						regulator bypass option: used as a supply voltage input for 3.3 V $\pm$ 10 % operation	
V <sub>CC(5.0)</sub>	14	14	16	14	-	internal regulator option: supply voltage input (4.0 V to 5.5 V); can be connected directly to USB supply $V_{BUS}$	
						regulator bypass option: connect to V <sub>reg(3.3)</sub>	
V <sub>pu(3.3)</sub>	15	15	1	15	-	pull-up supply voltage (3.3 V $\pm$ 10 %); connect an external 1.5 k $\Omega$ resistor on D+ (full-speed) or D– (low-speed); pin function is controlled by input SOFTCON	
						<b>SOFTCON = LOW</b> — $V_{pu(3.3)}$ floating (high impedance); ensures zero pull-up current	
						<b>SOFTCON = HIGH</b> — $V_{pu(3.3)}$ = 3.3 V; internally connected to $V_{reg(3.3)}$	
SOFTCON	16	16	2	16	I	software controlled USB connection input; a HIGH level applies 3.3 V to pin $V_{pu(3.3)}$ , which is connected to an external 1.5 k $\Omega$ pull-up resistor; this allows USB connect/disconnect signalling to be controlled by software	
						input pad; push pull; CMOS	

 Table 3.
 Pin description ...continued

[1] Symbol names with an overscore (e.g. NAME) indicate active LOW signals.

[2] ISP1105: ground terminal is connected to the exposed die pad (heat sink).



### 7. Functional description

#### 7.1 Function selection

#### Table 4. Function table

SUSPND	OE	(D+, D–)	RCV	VP/VM	Function
L	L	driving and receiving	active	active	normal driving (differential receiver active)
L	Н	receiving <sup>[1]</sup>	active	active	receiving
Η	L	driving	inactive <sup>[2]</sup>	active	driving during 'suspend' <u><sup>[3]</sup></u> (differential receiver inactive)
Н	Н	high-Z <mark>[1]</mark>	inactive <sup>[2]</sup>	active	low-power state

[1] Signal levels on (D+, D-) are determined by other USB devices and external pull-up/down resistors.

[2] In 'suspend' mode (SUSPND = HIGH) the differential receiver is inactive and output RCV is always LOW. Out-of-suspend ('K') signalling is detected via the single-ended receivers VP and VM.

[3] During suspend, the slew-rate control circuit of low-speed operation is disabled. The (D+, D–) lines are still driven to their intended states, without slew-rate control. This is permitted because driving during suspend is used to signal remote wake-up by driving a 'K' signal (one transition from idle to 'K' state) for a period of 1 to 15 ms.

### 7.2 Operating functions

# Table 5. Driving function (pin $\overline{OE} = L$ ) using single-ended input data interface for ISP1105 (pin MODE = L)

FSE0	VO	Data
L	L	differential logic 0
L	Н	differential logic 1
Н	L	SE0
Н	Н	SE0

# Table 6.Driving function (pin $\overline{OE} = L$ ) using differential input data interface for ISP1105<br/>(pin MODE = H) and ISP1106

u u	,	
VMO	VPO	Data
L	L	SE0
L	Н	differential logic 1
Н	L	differential logic 0
Н	Н	illegal state

#### Table 7. Receiving function (pin $\overline{OE} = H$ )

(D+, D–)	RCV	VP <sup>[1]</sup>	VM[1]
Differential logic 0	L	L	Н
Differential logic 1	Н	Н	L
SE0	RCV*[2]	L	L

[1] VP = VM = H indicates the sharing mode ( $V_{CC(5.0)}$  and  $V_{reg(3.3)}$  are disconnected).

[2] RCV\* denotes the signal level on output RCV just before SE0 state occurs. This level is stable during the SE0 period.





### 7.3 Power supply configurations

The ISP1105/1106 can be used with different power supply configurations, which can be changed dynamically. An overview is given in <u>Table 9</u>.

**Normal mode** — Both V<sub>CC(I/O)</sub> and V<sub>CC(5.0)</sub> or (V<sub>CC(5.0)</sub> and V<sub>reg(3.3)</sub>) are connected. For 5 V operation, V<sub>CC(5.0)</sub> is connected to a 5 V source (4.0 V to 5.5 V). The internal voltage regulator then produces 3.3 V for the USB connections. For 3.3 V operation, both V<sub>CC(5.0)</sub> and V<sub>reg(3.3)</sub> are connected to a 3.3 V source (3.0 V to 3.6 V). V<sub>CC(I/O)</sub> is independently connected to a voltage source (1.65 V to 3.6 V), depending on the supply voltage of the external circuit.

**Disable mode** —  $V_{CC(I/O)}$  is not connected,  $V_{CC(5.0)}$  or ( $V_{CC(5.0)}$  and  $V_{reg(3.3)}$ ) are connected. In this mode, the internal circuits of the ISP1105/1106 ensure that the (D+, D–) pins are in three-state and the power consumption drops to the low-power (suspended) state level. Some hysteresis is built into the detection of  $V_{CC(I/O)}$  lost.

**Sharing mode** — V<sub>CC(I/O)</sub> is connected, (V<sub>CC(5.0)</sub> and V<sub>reg(3.3)</sub>) are not connected. In this mode, the (D+, D–) pins are made three-state and the ISP1105/1106 allows external signals of up to 3.6 V to share the (D+, D–) lines. The internal circuits of the ISP1105/1106 ensure that virtually no current (maximum 10  $\mu$ A) is drawn via the (D+, D–) lines. The power consumption through pin V<sub>CC(I/O)</sub> drops to the low-power (suspended) state level. Both the VP and VM pins are driven HIGH to indicate this mode. Pin RCV is made LOW. Some hysteresis is built into the detection of V<sub>reg(3.3)</sub> lost.

#### Table 8. Pin states in disable or sharing mode

Pins	Disable mode state	Sharing mode state
V <sub>CC(5.0)</sub> / V <sub>reg(3.3)</sub>	5 V input / 3.3 V output; 3.3 V input / 3.3 V input	not present
V <sub>CC(I/O)</sub>	not present	1.65 V to 3.6 V input
V <sub>pu(3.3)</sub>	high impedance (off)	high impedance (off)
(D+, D–)	high impedance	high impedance
(VP, VM)	invalid <sup>[1]</sup>	Н
RCV	invalid <sup>[1]</sup>	L
Inputs (VO/VPO, FSE0/VMO, SPEED, MODE <sup>[2]</sup> , SUSPND, OE, SOFTCON)	high impedance	high impedance

[1] High impedance or driven LOW.

[2] ISP1105 only.

#### Table 9. Power supply configuration overview

$V_{CC(5.0)}$ or $V_{reg(3.3)}$	V <sub>CC(I/O)</sub>	Configuration	Special characteristics				
Connected	connected	normal mode	-				
Connected	not connected	disable mode	(D+, D–) and V <sub>pu(3.3)</sub> high impedance; VP, VM, RCV: invalid[ <u>1]</u>				
Not connected	connected	sharing mode	(D+, D–) and V <sub>pu(3.3)</sub> high impedance; VP, VM driven HIGH; RCV driven LOW				

[1] High impedance or driven LOW.

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### 7.4 Power supply input options

The ISP1105/1106 range has two power supply input options.

**Internal regulator** — V<sub>CC(5.0)</sub> is connected to 4.0 V to 5.5 V. The internal regulator is used to supply the internal circuitry with 3.3 V (nominal). The V<sub>reg(3.3)</sub> pin becomes a 3.3 V output reference.

**Regulator bypass** —  $V_{CC(5.0)}$  and  $V_{reg(3.3)}$  are connected to the same supply. The internal regulator is bypassed and the internal circuitry is supplied directly from the  $V_{reg(3.3)}$  power supply. The voltage range is 3.0 V to 3.6 V to comply with the USB specification.

The supply voltage range for each input option is specified in Table 10.

Input option	V <sub>CC(5.0)</sub>	V <sub>reg(3.3)</sub>	V <sub>CC(I/O)</sub>
Internal regulator	supply input for internal regulator (4.0 V to 5.5 V)	voltage reference output (3.3 V, 300 μA)	supply input for digital I/O pins (1.65 V to 3.6 V)
Regulator bypass	connected to $V_{reg(3.3)}$ with maximum voltage drop of 0.3 V (2.7 V to 3.6 V)	supply input (3.0 V to 3.6 V)	supply input for digital I/O pins (1.65 V to 3.6 V)

Table 10. Power supply input options



### 8. Electrostatic discharge (ESD)

### 8.1 ESD protection

The pins that are connected to the USB connector (D+, D–, V<sub>CC(5.0)</sub> and GND) have a minimum of ±12 kV ESD protection. The ±12 kV measurement is limited by the test equipment. Capacitors of 4.7  $\mu$ F connected from V<sub>reg(3.3)</sub> to GND and V<sub>CC(5.0)</sub> to GND are required to achieve this ±12 kV ESD protection (see Figure 6).



#### 8.2 ESD test conditions

A detailed report on test set-up and results is available on request.



### 9. Limiting values

#### Table 11. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Мах	Unit
V <sub>CC(5.0)</sub>	supply voltage		-0.5	+6.0	V
V <sub>CC(I/O)</sub>	I/O supply voltage		-0.5	+4.6	V
V <sub>reg(3.3)</sub>	regulated supply voltage		-0.5	+4.6	V
VI	DC input voltage		-0.5	$V_{CC(I/O)} + 0.5$	V
l <sub>lu</sub>	latch-up current	$V_I = -1.8 \text{ V}$ to 5.4 V	-	100	mA
V <sub>esd</sub>	electrostatic discharge voltage	I <sub>LI</sub> < 1 μΑ	<u>[1][2]</u>		
		on pins D+, D–, V <sub>CC(5.0)</sub> and GND	-12000	+12000	V
		on other pins	-2000	+2000	V
T <sub>stg</sub>	storage temperature		-40	+125	°C

[1] Testing equipment limits measurement to only  $\pm 12$  kV. Capacitors needed on V<sub>CC(5.0)</sub> and V<sub>reg(3.3)</sub>; see Section 8.

[2] Equivalent to discharging a 100 pF capacitor via a 1.5 k $\Omega$  resistor (Human Body Model).

### 10. Recommended operating conditions

#### Table 12. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>CC(5.0)</sub>	supply voltage (internal regulator option)	5 V operation	4.0	5.0	5.5	V
V <sub>reg(3.3)</sub>	supply voltage (regulator bypass option)	3.3 V operation	3.0	3.3	3.6	V
V <sub>CC(I/O)</sub>	I/O supply voltage		1.65	-	3.6	V
VI	input voltage		0	-	V <sub>CC(I/O)</sub>	V
V <sub>I(AI/O)</sub>	input voltage on analog I/O pins (D+/D–)		0	-	3.6	V
T <sub>amb</sub>	operating ambient temperatur	e	-40	-	+85	°C



### **11. Static characteristics**

#### Table 13. Static characteristics: supply pins

 $V_{CC} = 4.0 \text{ V}$  to 5.5 V or  $V_{reg(3.3)} = 3.0 \text{ V}$  to 3.6 V;  $V_{CC(I/O)} = 1.65 \text{ V}$  to 3.6 V;  $V_{GND} = 0 \text{ V}$ ; see <u>Table 10</u> for valid voltage level combinations;  $T_{amb} = -40 \text{ °C}$  to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V <sub>reg(3.3)</sub>	regulated supply voltage output	internal regulator option; $I_{load} \leq 300 \ \mu A$	<u>[1][2]</u>	3.0	3.3	3.6	V
I <sub>CC</sub>	operating supply current	full-speed transmitting and receiving at 12 Mbit/s; $C_L = 50 \text{ pF}$ on D+/D–	[3]	-	4	8	mA
I <sub>CC(I/O)</sub>	operating I/O supply current	full-speed transmitting and receiving at 12 Mbit/s	[3]	-	1	2	mA
I <sub>CC(idle)</sub>	supply current during full-speed idle and SE0	full-speed idle: V_{D+} > 2.7 V, V_{D-} < 0.3 V; SE0: V_{D+} < 0.3 V, V_{D-} < 0.3 V	<u>[4]</u>	-	-	500	μΑ
I <sub>CC(I/O)(static)</sub>	static I/O supply current	full-speed idle, SE0 or suspend		-	-	20	μA
I <sub>CC(susp)</sub>	suspend supply current	SUSPND = HIGH	[4]	-	-	20	μA
I <sub>CC(dis)</sub>	disable mode supply current	V <sub>CC(I/O)</sub> not connected	[4]	-	-	20	μΑ
I <sub>CC(I/O)</sub> (sharing)	sharing mode I/O supply current	$V_{CC(5.0)} \text{ or } V_{reg(3.3)} \text{ not connected}$		-	-	20	μA
I <sub>Dx(sharing)</sub>	sharing mode load current on pins D+ and D–	$V_{CC(5.0)}$ or $V_{reg(3.3)}$ not connected; SOFTCON = LOW; $V_{Dx} = 3.6 V$		-	-	10	μA
V <sub>reg(3.3)th</sub>	regulated supply voltage detection threshold	$\begin{array}{l} 1.65 \ V \leq V_{CC(I/O)} \leq V_{reg(3.3)}; \\ 2.7 \ V \leq V_{reg(3.3)} \leq 3.6 \ V \end{array}$					
		supply lost		-	-	0.8	V
		supply present	[5]	2.4	-	-	V
V <sub>reg(3.3)hys</sub>	regulated supply voltage detection hysteresis	V <sub>CC(I/O)</sub> = 1.8 V		-	0.45	-	V
V <sub>CC(I/O)th</sub>	I/O supply voltage detection	V <sub>reg(3.3)</sub> = 2.7 V to 3.6 V					
	threshold	supply lost		-	-	0.5	V
		supply present		1.4	-	-	V
V <sub>CC(I/O)hys</sub>	I/O supply voltage detection hysteresis	V <sub>reg(3.3)</sub> = 3.3 V		-	0.45	-	V

[1]  $I_{load}$  includes the pull-up resistor current via pin  $V_{pu(3.3)}$ .

[2] In 'suspend' mode, the minimum voltage is 2.7 V.

[3] Maximum value is characterized only, not tested in production.

[4] Excluding any load current and  $V_{pu(3.3)}/V_{sw}$  source current to the 1.5 k $\Omega$  and 15 k $\Omega$  pull-up and pull-down resistors (200  $\mu$ A typ.).

[5] When  $V_{CC(I/O)}$  < 2.7 V, the minimum value for  $V_{th(reg3.3)(present)}$  is 2.0 V.



**Table 14.** Static characteristics: digital pins  $V_{CC(I/O)} = 1.65 \text{ V to } 3.6 \text{ V}; V_{GND} = 0 \text{ V}; T_{amb} = -40 \text{ °C to } +85 \text{ °C}; unless otherwise specified.$ 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>CC(I/O)</sub> =	1.65 to 3.6 V					
Input leve	ls					
V <sub>IL</sub>	LOW-level input voltage		-	-	0.3V <sub>CC(I/O)</sub>	V
V <sub>IH</sub>	HIGH-level input voltage		0.6V <sub>CC(I/O)</sub>	-	-	V
Output lev	vels					
V <sub>OL</sub>	LOW-level output voltage	I <sub>OL</sub> = 100 μA	-	-	0.15	V
		$I_{OL} = 2 \text{ mA}$	-	-	0.4	V
V <sub>он</sub>	HIGH-level output voltage	I <sub>OH</sub> = 100 μA	$V_{CC(I/O)} - 0.15$	-	-	V
		I <sub>OH</sub> = 2 mA	$V_{CC(I/O)} - 0.4$	-	-	V
Leakage o	current					
I <sub>LI</sub>	input leakage current		-1	-	+1	μA
Example	1: $V_{CC(I/O)}$ = 1.8 V $\pm$ 0.15 V					
Input leve	( )					
V <sub>IL</sub>	LOW-level input voltage		-	-	0.5	V
V <sub>IH</sub>	HIGH-level input voltage		1.2	-	-	V
Output lev	vels					
V <sub>OL</sub>	LOW-level output voltage	I <sub>OL</sub> = 100 μA	-	-	0.15	V
		$I_{OL} = 2 \text{ mA}$	-	-	0.4	V
V <sub>он</sub>	HIGH-level output voltage	I <sub>OH</sub> = 100 μA	1.5	-	-	V
		I <sub>OH</sub> = 2 mA	1.25	-	-	V
Example	2: $V_{CC(I/O)}$ = 2.5 V $\pm$ 0.2 V					
	2: V <sub>CC(I/O)</sub> = 2.5 V ± 0.2 V Is					
Input leve	( )		-	-	0.7	V
Input leve V <sub>IL</sub>	LOW-level input voltage			-	0.7	V V
Input level V <sub>IL</sub> V <sub>IH</sub>	LOW-level input voltage HIGH-level input voltage		-	-		
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev	LOW-level input voltage HIGH-level input voltage		-	- -		
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev	LOW-level input voltage HIGH-level input voltage	I <sub>OL</sub> = 100 μA	- 1.7	-	- 0.15	V V
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub>	LOW-level input voltage HIGH-level input voltage Vels LOW-level output voltage	$\frac{I_{OL} = 100 \ \mu A}{I_{OL} = 2 \ mA}$	- 1.7 -	-	-	V V V
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub>	LOW-level input voltage HIGH-level input voltage	I <sub>OL</sub> = 100 μA I <sub>OL</sub> = 2 mA I <sub>OH</sub> = 100 μA	- 1.7 - - 2.15	-	- 0.15 0.4	V V V V
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub> V <sub>OH</sub>	LOW-level input voltage HIGH-level input voltage LOW-level output voltage HIGH-level output voltage	$\frac{I_{OL} = 100 \ \mu A}{I_{OL} = 2 \ mA}$	- 1.7 -	-	- 0.15 0.4	V V V
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub> Voн	LOW-level input voltage HIGH-level input voltage LOW-level output voltage HIGH-level output voltage	I <sub>OL</sub> = 100 μA I <sub>OL</sub> = 2 mA I <sub>OH</sub> = 100 μA	- 1.7 - - 2.15	-	- 0.15 0.4	V V V V
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub> V <sub>OH</sub> Example Input level	IS LOW-level input voltage HIGH-level input voltage LOW-level output voltage HIGH-level output voltage 3: V <sub>CC(I/O)</sub> = 3.3 V ± 0.3 V IS	I <sub>OL</sub> = 100 μA I <sub>OL</sub> = 2 mA I <sub>OH</sub> = 100 μA	- 1.7 - - 2.15	-	- 0.15 0.4 - -	V V V V
Input level V <sub>IL</sub> Output lev V <sub>OL</sub> Example Input level V <sub>IL</sub>	LOW-level input voltage HIGH-level input voltage LOW-level output voltage HIGH-level output voltage 3: V <sub>CC(I/O)</sub> = 3.3 V ± 0.3 V LOW-level input voltage	I <sub>OL</sub> = 100 μA I <sub>OL</sub> = 2 mA I <sub>OH</sub> = 100 μA	- 1.7 - 2.15 1.9	- - -	- 0.15 0.4	V V V V
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub> V <sub>OH</sub> Example Input level V <sub>IL</sub> V <sub>IH</sub>	IS LOW-level input voltage HIGH-level input voltage LOW-level output voltage HIGH-level output voltage 3: V <sub>CC(I/O)</sub> = 3.3 V ± 0.3 V IS LOW-level input voltage HIGH-level input voltage	I <sub>OL</sub> = 100 μA I <sub>OL</sub> = 2 mA I <sub>OH</sub> = 100 μA	- 1.7 - - 2.15 1.9		- 0.15 0.4 - -	V V V V
Input level V <sub>IL</sub> Output lev V <sub>OL</sub> VOH Example Input level V <sub>IL</sub> VIH Output level	IS LOW-level input voltage HIGH-level input voltage LOW-level output voltage HIGH-level output voltage 3: V <sub>CC(I/O)</sub> = 3.3 V ± 0.3 V IS LOW-level input voltage HIGH-level input voltage	$I_{OL} = 100 \ \mu A$ $I_{OL} = 2 \ m A$ $I_{OH} = 100 \ \mu A$ $I_{OH} = 2 \ m A$	- 1.7 - 2.15 1.9		- 0.15 0.4 - - 0.9 -	V V V V V
Input level VIL VIH Output lev VoL VoH Example Input level VIL VIH Output lev	IS LOW-level input voltage HIGH-level input voltage LOW-level output voltage HIGH-level output voltage 3: V <sub>CC(I/O)</sub> = 3.3 V ± 0.3 V IS LOW-level input voltage HIGH-level input voltage	$I_{OL} = 100 \ \mu A$ $I_{OL} = 2 \ m A$ $I_{OH} = 100 \ \mu A$ $I_{OH} = 2 \ m A$ $I_{OH} = 100 \ \mu A$	- 1.7 - 2.15 1.9 - 2.15 - 2.15 -	- - - -	- 0.15 0.4 - - 0.9 - 0.15	V V V V V V
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub> VOH Example Input level V <sub>IL</sub> VIH Output lev VoL	IS LOW-level input voltage HIGH-level input voltage Vels LOW-level output voltage HIGH-level output voltage 3: V <sub>CC(VO)</sub> = 3.3 V ± 0.3 V IS LOW-level input voltage HIGH-level input voltage Vels LOW-level output voltage	$I_{OL} = 100 \ \mu A$ $I_{OL} = 2 \ m A$ $I_{OH} = 100 \ \mu A$ $I_{OH} = 2 \ m A$ $I_{OL} = 2 \ m A$	- 1.7 - 2.15 1.9 - 2.15 - 2.15 -	- - - - - -	- 0.15 0.4 - - 0.9 - 0.15 0.4	V V V V V V V V V
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub> VOH Example Input level V <sub>IL</sub> VIH Output lev VoL	IS LOW-level input voltage HIGH-level input voltage LOW-level output voltage HIGH-level output voltage 3: V <sub>CC(I/O)</sub> = 3.3 V ± 0.3 V IS LOW-level input voltage HIGH-level input voltage	$I_{OL} = 100 \ \mu A$ $I_{OL} = 2 \ m A$ $I_{OH} = 100 \ \mu A$ $I_{OH} = 2 \ m A$ $I_{OL} = 2 \ m A$ $I_{OL} = 100 \ \mu A$ $I_{OL} = 2 \ m A$ $I_{OL} = 100 \ \mu A$	- 1.7 - 2.15 1.9 - 2.15 1.9 - 2.15 - 2.15 - 2.85	- - - - - - - - - - - - - - - - -	- 0.15 0.4 - - 0.9 - 0.15 0.4 -	V V V V V V V V V V
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub> V <sub>OH</sub> Example Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub> V <sub>OH</sub>	IS LOW-level input voltage HIGH-level input voltage KOW-level output voltage HIGH-level output voltage S: V <sub>CC(I/O)</sub> = 3.3 V ± 0.3 V IS LOW-level input voltage HIGH-level input voltage KOW-level output voltage HIGH-level output voltage	$I_{OL} = 100 \ \mu A$ $I_{OL} = 2 \ m A$ $I_{OH} = 100 \ \mu A$ $I_{OH} = 2 \ m A$ $I_{OL} = 2 \ m A$	- 1.7 - 2.15 1.9 - 2.15 - 2.15 -	- - - - - - - -	- 0.15 0.4 - - 0.9 - 0.15 0.4	V V V V V V V V V
Input level V <sub>IL</sub> V <sub>IH</sub> Output lev V <sub>OL</sub> V <sub>OH</sub>	IS LOW-level input voltage HIGH-level input voltage KOW-level output voltage HIGH-level output voltage S: V <sub>CC(I/O)</sub> = 3.3 V ± 0.3 V IS LOW-level input voltage HIGH-level input voltage KOW-level output voltage HIGH-level output voltage	$I_{OL} = 100 \ \mu A$ $I_{OL} = 2 \ m A$ $I_{OH} = 100 \ \mu A$ $I_{OH} = 2 \ m A$ $I_{OL} = 2 \ m A$ $I_{OL} = 100 \ \mu A$ $I_{OL} = 2 \ m A$ $I_{OL} = 100 \ \mu A$	- 1.7 - 2.15 1.9 - 2.15 1.9 - 2.15 - 2.15 - 2.85	- - - - - - - - - - - - - - - - -	- 0.15 0.4 - - 0.9 - 0.15 0.4 -	V V V V V V V V V V



Symbol	Parameter	Conditions		Min	Тур	Мах	Unit
Input level	S						
Differential	receiver						
V <sub>DI</sub>	differential input sensitivity	$ V_{I(D+)}-V_{I(D-)} $		0.2	-	-	V
V <sub>CM</sub>	differential common mode voltage	includes V <sub>DI</sub> range		0.8	-	2.5	V
Single-ende	ed receiver						
VIL	LOW-level input voltage			-	-	0.8	V
V <sub>IH</sub>	HIGH-level input voltage			2.0	-	-	V
V <sub>hys</sub>	hysteresis voltage			0.4	-	0.7	V
Output lev	els						
V <sub>OL</sub>	LOW-level output voltage	$R_L$ = 1.5 k $\Omega$ to +3.6 V		-	-	0.3	V
V <sub>OH</sub>	HIGH-level output voltage	$R_L$ = 15 k $\Omega$ to GND	<u>[1]</u>	2.8	-	3.6	V
Leakage c	urrent						
I <sub>LZ</sub>	OFF-state leakage current			-1	-	+1	μA
Capacitanc	e						
C <sub>IN</sub>	transceiver capacitance	pin to GND		-	-	20	pF
Resistance	•						
Z <sub>DRV</sub>	driver output impedance	steady-state drive	[2]	34	39	44	Ω
Z <sub>INP</sub>	input impedance			10	-	-	MΩ
R <sub>SW</sub>	internal switch resistance at pin $V_{\text{pu}(3.3)}$			-	-	10	Ω
Terminatio	n						
V <sub>TERM</sub>	termination voltage for upstream port pull-up (R <sub>PU</sub> )		<u>[3][4]</u>	3.0	-	3.6	V

#### Table 15. Static characteristics: analog I/O pins (D+, D–)

[1]  $V_{OH(min)} = V_{reg(3.3)} - 0.2 V.$ 

[2] Includes external resistors of 33  $\Omega \pm 1$  % on both D+ and D-.

[3] This voltage is available at pins  $V_{reg(3.3)}$  and  $V_{pu(3.3)}$ .

[4] In 'suspend' mode the minimum voltage is 2.7 V.



### **12. Dynamic characteristics**

#### Table 16. Dynamic characteristics: analog I/O pins (D+, D-)

 $V_{CC} = 4.0 \text{ V to } 5.5 \text{ V or } V_{reg(3.3)} = 3.0 \text{ V to } 3.6 \text{ V}; V_{CC(I/O)} = 1.65 \text{ V to } 3.6 \text{ V}; V_{GND} = 0 \text{ V}; \text{ see } \underline{\text{Table 10}}$  for valid voltage level combinations;  $T_{amb} = -40 \text{ °C to } +85 \text{ °C};$  unless otherwise specified.[1]

Symbol	Parameter	Conditions		Min	Тур	Мах	Unit
Driver cha	aracteristics						
Full-speed	I mode						
t <sub>FR</sub>	rise time	$C_L$ = 50 pF to 125 pF; 10 % to 90 % of $ V_{OH}-V_{OL} ;$ see $\underline{Figure~7}$		4	-	20	ns
t <sub>FF</sub>	fall time	$C_L$ = 50 pF to 125 pF; 90 % to 10 % of $ V_{OH}-V_{OL} ;$ see $\underline{Figure~7}$		4	-	20	ns
FRFM	differential rise/fall time matching (t <sub>FR</sub> /t <sub>FF</sub> )	excluding the first transition from idle state		90	-	111.1	%
V <sub>CRS</sub>	output signal crossover voltage	excluding the first transition from idle state; see Figure 10	[2]	1.3	-	2.0	V
Low-speed	d mode						
t <sub>LR</sub>	rise time	$C_L$ = 50 pF to 600 pF; 10 % to 90 % of $ V_{OH}-V_{OL} ;$ see <u>Figure 7</u>		75	-	300	ns
t <sub>LF</sub>	fall time	$C_L$ = 50 pF to 600 pF; 90 % to 10 % of $ V_{OH}-V_{OL} ;$ see $\underline{Figure~7}$		75	-	300	ns
LRFM	differential rise/fall time matching (t <sub>LR</sub> /t <sub>LF</sub> )	excluding the first transition from idle state		80	-	125	%
V <sub>CRS</sub>	output signal crossover voltage	excluding the first transition from idle state; see Figure 10	[2]	1.3	-	2.0	V
Driver tim	ing						
Full-speed	l mode						
t <sub>PLH(drv)</sub>	driver propagation delay (VO/VPO, FSE0/VMO to D+,D-)	LOW-to-HIGH; see Figure 10		-	-	18	ns
t <sub>PHL(drv)</sub>	driver propagation delay (VO/VPO, FSE0/VMO to D+,D–)	HIGH-to-LOW; see Figure 10		-	-	18	ns
t <sub>PHZ</sub>	driver disable delay ( $\overline{OE}$ to D+,D–)	HIGH-to-OFF; see Figure 8		-	-	15	ns
t <sub>PLZ</sub>	driver disable delay (OE to D+,D–)	LOW-to-OFF; see Figure 8		-	-	15	ns
t <sub>PZH</sub>	driver enable delay (OE to D+,D–)	OFF-to-HIGH; see Figure 8		-	-	15	ns
t <sub>PZL</sub>	driver enable delay (OE to D+,D–)	OFF-to-LOW; see Figure 8		-	-	15	ns
Low-speed	d mode						

Not specified: low-speed delay timings are dominated by the slow rise/fall times t<sub>LR</sub> and t<sub>LF</sub>.

#### Table 16. Dynamic characteristics: analog I/O pins (D+, D-) ... continued

 $V_{CC} = 4.0 \text{ V}$  to 5.5 V or  $V_{reg(3.3)} = 3.0 \text{ V}$  to 3.6 V;  $V_{CC(I/O)} = 1.65 \text{ V}$  to 3.6 V;  $V_{GND} = 0 \text{ V}$ ; see <u>Table 10</u> for valid voltage level combinations;  $T_{amb} = -40 \text{ °C}$  to +85 °C; unless otherwise specified.[1]

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Receiver	timings (full-speed and	low-speed mode)				
Differentia	l receiver					
t <sub>PLH(rcv)</sub>	propagation delay (D+,D– to RCV)	LOW-to-HIGH; see Figure 9	-	-	15	ns
t <sub>PHL(rcv)</sub>	propagation delay (D+,D– to RCV)	HIGH-to-LOW; see Figure 9	-	-	15	ns
Single-end	ded receiver					
t <sub>PLH(se)</sub>	propagation delay (D+,D– to VP, VM)	LOW-to-HIGH; see Figure 9	-	-	18	ns
t <sub>PHL(se)</sub>	propagation delay (D+,D– to VP, VM)	HIGH-to-LOW; see Figure 9	-	-	18	ns

[1] Test circuit: see Figure 13.

[2] Characterized only, not tested. Limits guaranteed by design.





### 13. Test information









### 14. Package outline



#### Fig 14. HBCC16 package outline.





#### HVQFN16: plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 x 3 x 0.85 mm

#### Fig 15. HVQFN16 package outline.

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#### Fig 16. TSSOP16 package outline.

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### **15. Revision history**

#### Table 17. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
ISP1105_1106_10	20090928	Product data sheet	-	ISP1105_1106_9
Modifications:	Rebrande	d to the ST-Ericsson template.		
	Section 2	"Features": updated.		
	Section 4	"Ordering information": updated.		
	<ul> <li>Removed</li> </ul>	packing information.		
	<ul> <li>Removed</li> </ul>	soldering information.		
ISP1105_1106_9	20090119	Product data sheet	-	ISP1105_1106-08
ISP1105_1106-08 (9397 750 09529)	20040219	Product data	-	ISP1105_1106_1107-07
SP1105_1106_1107-07 9397 750 08872)	20020329	Product data	-	ISP1105_1106_1107-06
SP1105_1106_1107-06 (9397 750 08681)	20011130	Product data	-	ISP1105_1106_1107-05
SP1105_1106_1107-05 9397 750 08643)	20010903	Product data	-	ISP1105_1106_1107-04
SP1105_1106_1107-04 9397 750 08515)	20010802	Preliminary data	-	ISP1105_1106_1107-03
SP1105_1106_1107-03 9397 750 07879)	20010704	Preliminary data	-	ISP1107-02
SP1107-02 9397 750 06899)	20010205	Objective specification; ISP1107 stand-alone data sheet only	-	ISP1107-01
SP1107-01 9397 750 08643)	20000223	Objective specification; ISP1107 stand-alone data sheet only		-



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Product data sheet